

Link do produktu: <https://serwisowe.pl/sciezki-pady-naprawa-pcb-uszkodzen-szybko-dzieki-mechanic-magic-tag-2780el-p-12250.html>

ŚCIEŻKI PADY NAPRAWA PCB USZKODZEŃ SZYBKO DZIĘKI MECHANIC MAGIC TAG 2780el

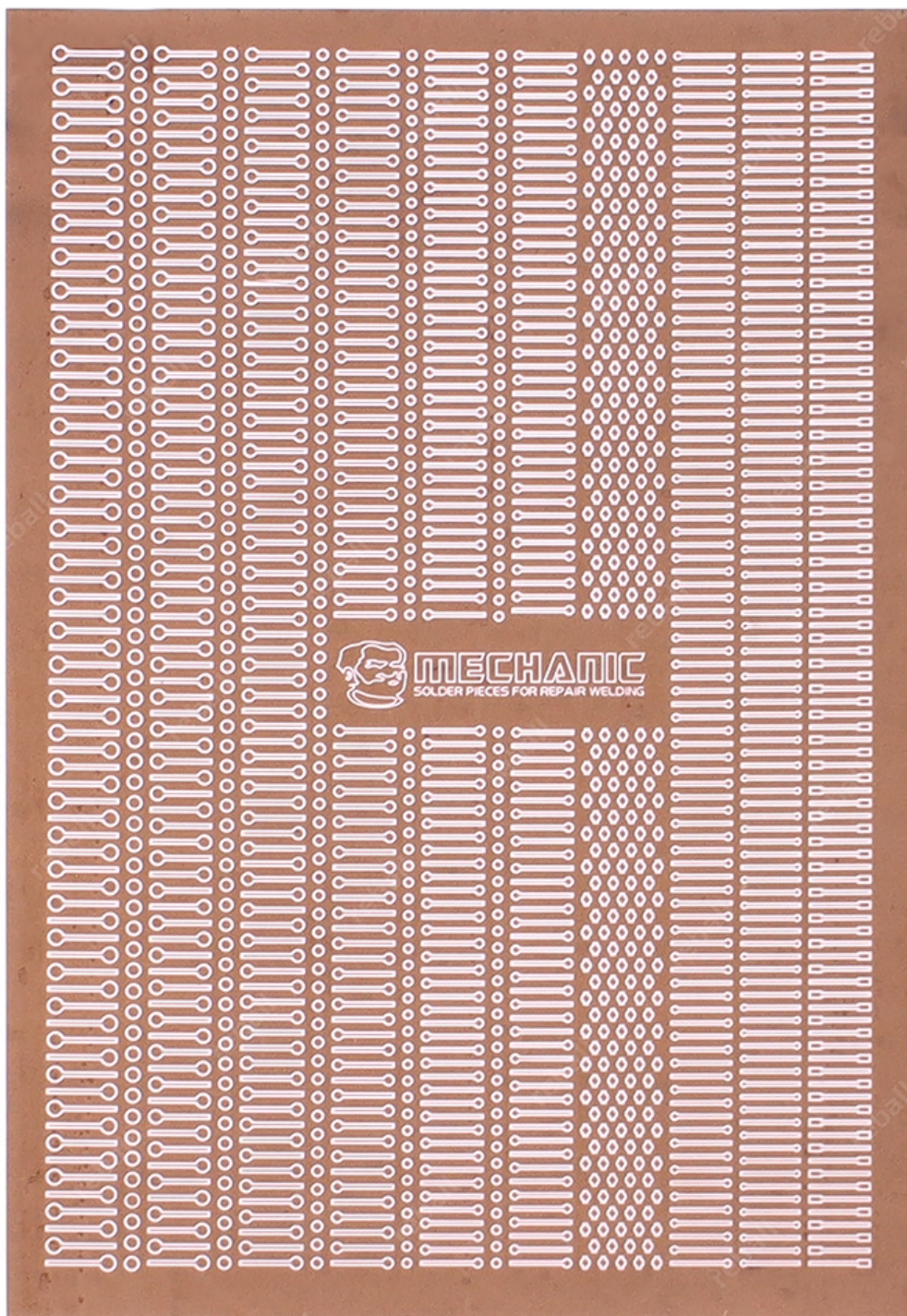
Cena brutto	49,00 zł
Cena netto	39,84 zł
Dostępność	Dostępny
Czas wysyłki	24 godziny
Numer katalogowy	XAK00494
Kod EAN	5903815926167

Opis produktu

AK00494

ZESTAW 2780 PADÓW I ELEMENTÓW ŚCIEŻEK DO NAPRAWY LAMINATÓW PCB

MECHANIC MAGIC TAG - 2nd GENERATION



MECHANIC Magic Tag to zestaw **2780 elementów** tj pady czy ścieżki z padami w różnych rozmiarach do naprawy laminatów PCB w sytuacji kiedy doszło do uszkodzenia w/w elementów.

Pady można przylutować w miejscach uszkodzenia (kiedy wyprowadzenia z warstw laminatu są dostępne) jak i przykleić np. na **lakier UV** dostępny w naszej ofercie w różnych kolorach.

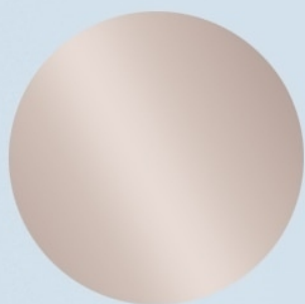
Zestaw szczególnie polecany do naprawy:

- laminatów w telefonach komórkowych, tabletach bądź laptopach.
- regeneracji padów układów BGA.

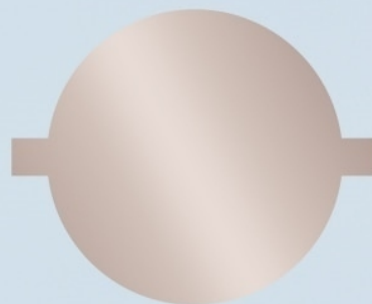
Grubość miedzianych ścieżek to tylko 30um.

Więcej informacji o zastosowaniu i sposobie używania zestawu **Mechanic Magic Tag** znajdziesz na YouTube.

Add a fixed pin on the original pad to prevent the solder piece from falling off



1st generation
without fixed pin



2nd generation
with fixed pin



1st generation
thickness: 60µm



2nd generation
thickness: 30µm

Various shape and specifications, suitable for different pad with dropped solder joint



补点焊盘
SOLDER PIECE
for Repair Welding

替代传统飞线打圈补点，还原原装焊盘效果，无痕修复。
Replace the traditional circling of jump wire to filled the missing solder joint, restore to the original pad and without trace.



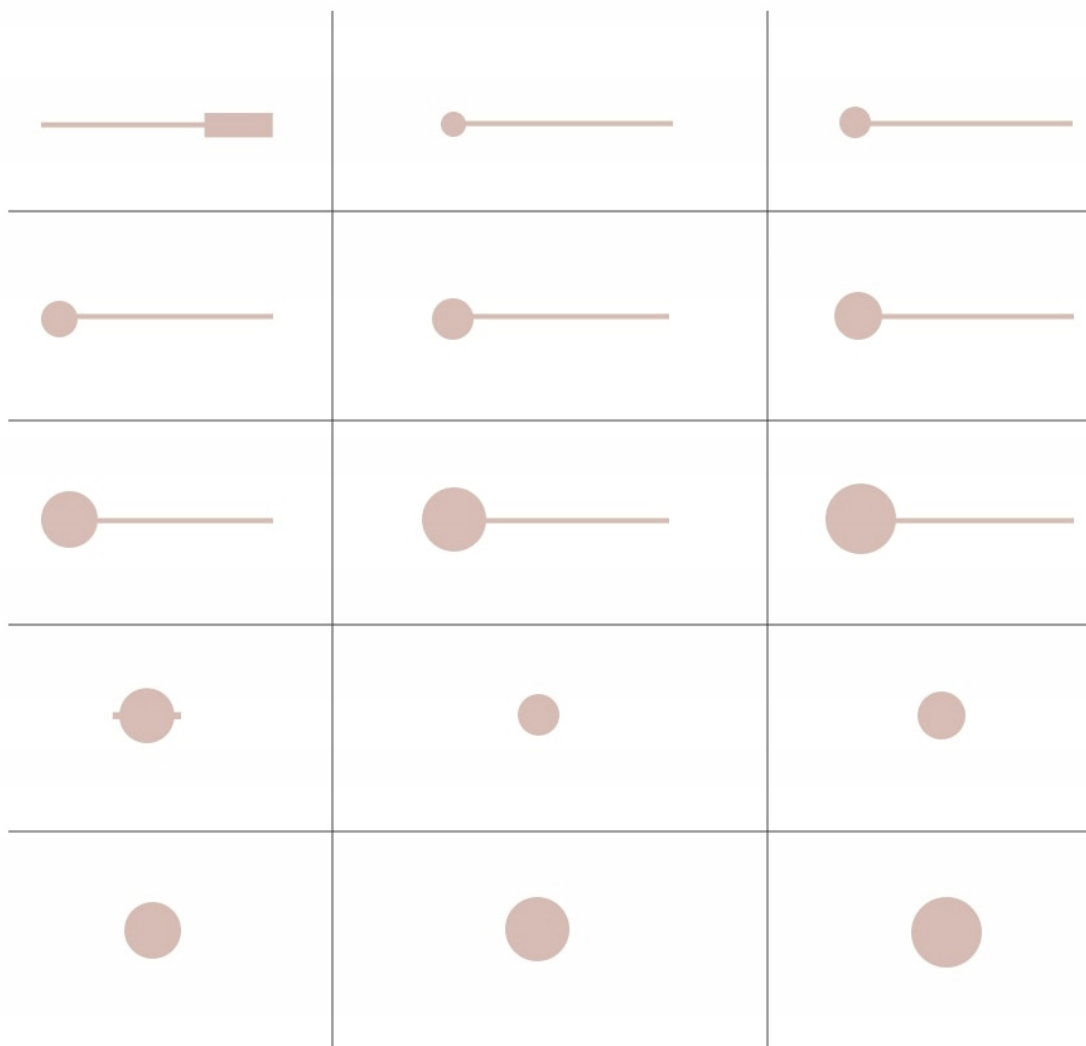
Magic Tag



增强固定引脚
Fixed Pin Of Pad

超薄贴片体验
Ultra-thin Experience

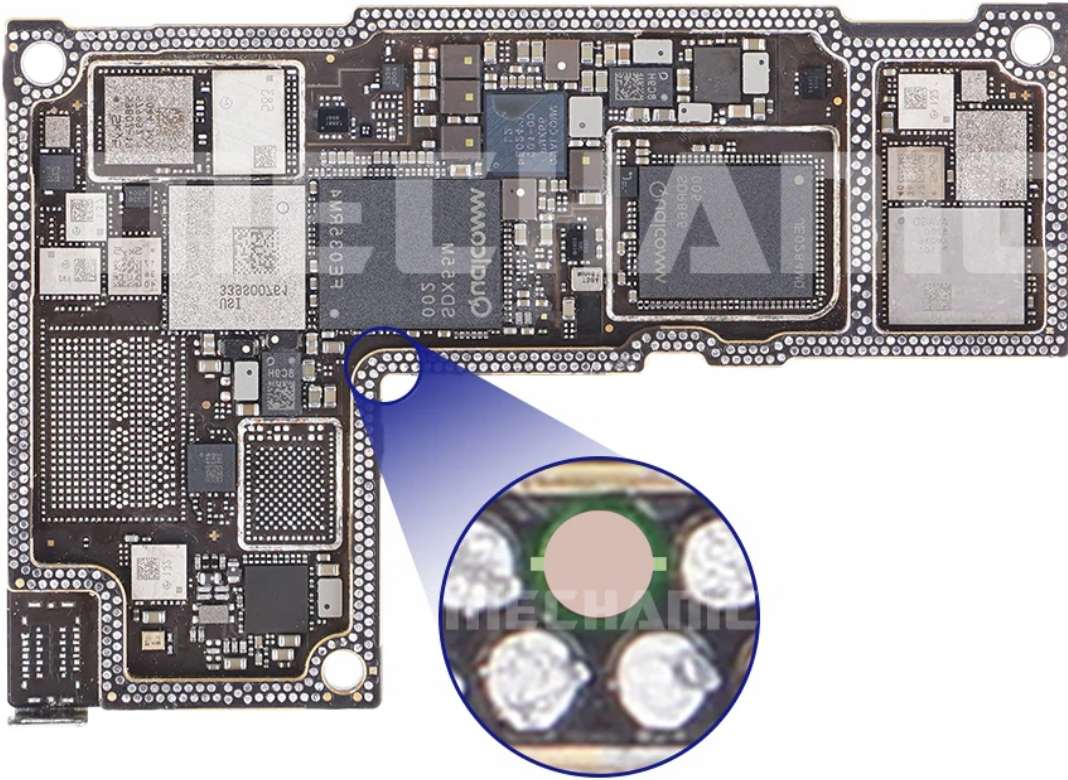
Suitable for pads with different size



Used in the repair field, like the IC pad of the mobile phone motherboard or the middle layer of the double-layer motherboard/CPU/WIFI/hard disk/big audio/touch IC/ and other pads. Repair the falling part of the pad due to drop, shock or extrusion, restore to the original pad and make it more stable!



2nd generation



- The pads are reinforced with fixed pins and will never fall off.
- It adopts industrial-grade printed circuit board copper foil with a thickness of 30 μ m.
- Good flatness, which can prevent pseudo soldering effectively caused by unevenness.
- The BGA bonding surface has high saturation, stable electrical performance, good welding strength, and it is not easy to drop off and unsoldering.
- The connection joint with the circuit is firm, and can fixed the green oil (UV curing solder mask ink) well.
- It saves time and effort and no need to circle during jumping wire so the repair efficiency is relatively high.



2ND GENERATION ENHANCED VERSION

New technology of repair welding Enhanced fixed pin Ultra-thin mounting

Mechanic Rework Pad for Repair Welding

Replace the traditional circling of jump wire to filled the missing solder joint
restore to the original pad and without trace



Magic Tag

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- Good flatness, which can prevent pseudo soldering effectively caused by unevenness.
- The BGA bonding surface has high saturation, stable electrical performance, good welding strength, and it is not easy to drop off and unsoldering.
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This product has passed the national intellectual property special technical certification
Patent NO: 202030759480.6



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